

FEATURES

- Meets or Exceeds the Requirements of IBM® 360/370 Input/Output Interface Specification for 4.5-Mb/s Operation
- Single 5-V Supply
- Uncommitted Emitter-Follower Output Structure for Party-Line Operation
- Driver Output Short-Circuit Protection
- Driver Input/Receiver Output Compatible With TTL
- Receiver Input Resistance . . . 7.4 k Ω to 20 k Ω
- Ratio Specification for Propagation Delay Time, Low to High/High to Low

DESCRIPTION/ ORDERING INFORMATION

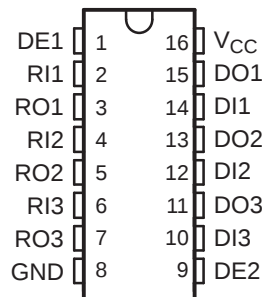
The SN751730 triple line driver/receiver is specifically designed to meet the input/output interface specifications for IBM System 360/370. It also is compatible with standard TTL logic and supply voltage levels.

The low-impedance emitter-follower driver outputs of the SN751730 drive terminated lines, such as coaxial cable or twisted pair. Having the outputs uncommitted allows wired-OR logic to be performed in party-line applications. Output short-circuit protection is provided by an internal clamping network that turns on when the output voltage drops below approximately 2.5 V.

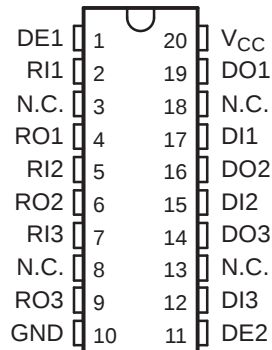
An open line affects the receiver input as does a low-level input voltage.

All the driver inputs and receiver outputs are in conventional TTL configuration and the gating can be used during power-up and power-down sequences to ensure that no noise is introduced to the line by pulling either DE1 or DE2 to a low level.

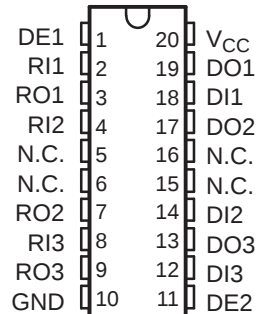
**D OR N PACKAGE
(TOP VIEW)**



**DW PACKAGE
(TOP VIEW)**



**NS PACKAGE
(TOP VIEW)**



N.C. – No internal connection



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SN751730

TRIPLE LINE DRIVER/RECEIVER

SLLS062E–MAY 1990–REVISED AUGUST 2007

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN751730N	SN751730N
	SOIC – D	Tube	SN751730D	SN751730
		Tape and reel	SN751730DR	
	SOIC – DW	Tube	SN751730DW	SN751730
		Tape and reel	SN751730DWR	
	SOP – NS	Tape and reel	SN751730NSR	SN751730

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

FUNCTION TABLES

EACH DRIVER

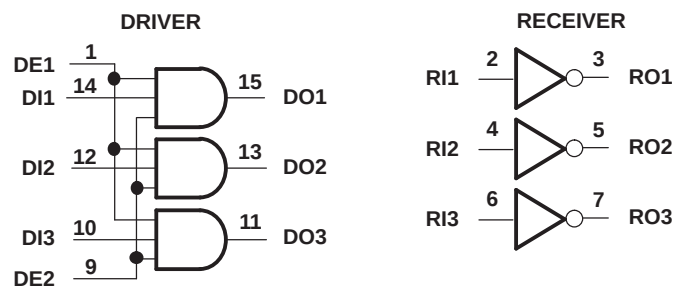
INPUTS			OUTPUT DO
DI	DE1	DE2	
L	X	X	L
X	L	X	L
X	X	L	L
H	H	H	H

EACH DRIVER⁽¹⁾

INPUT RI	OUTPUT RO
L	H
H	L
Open	H

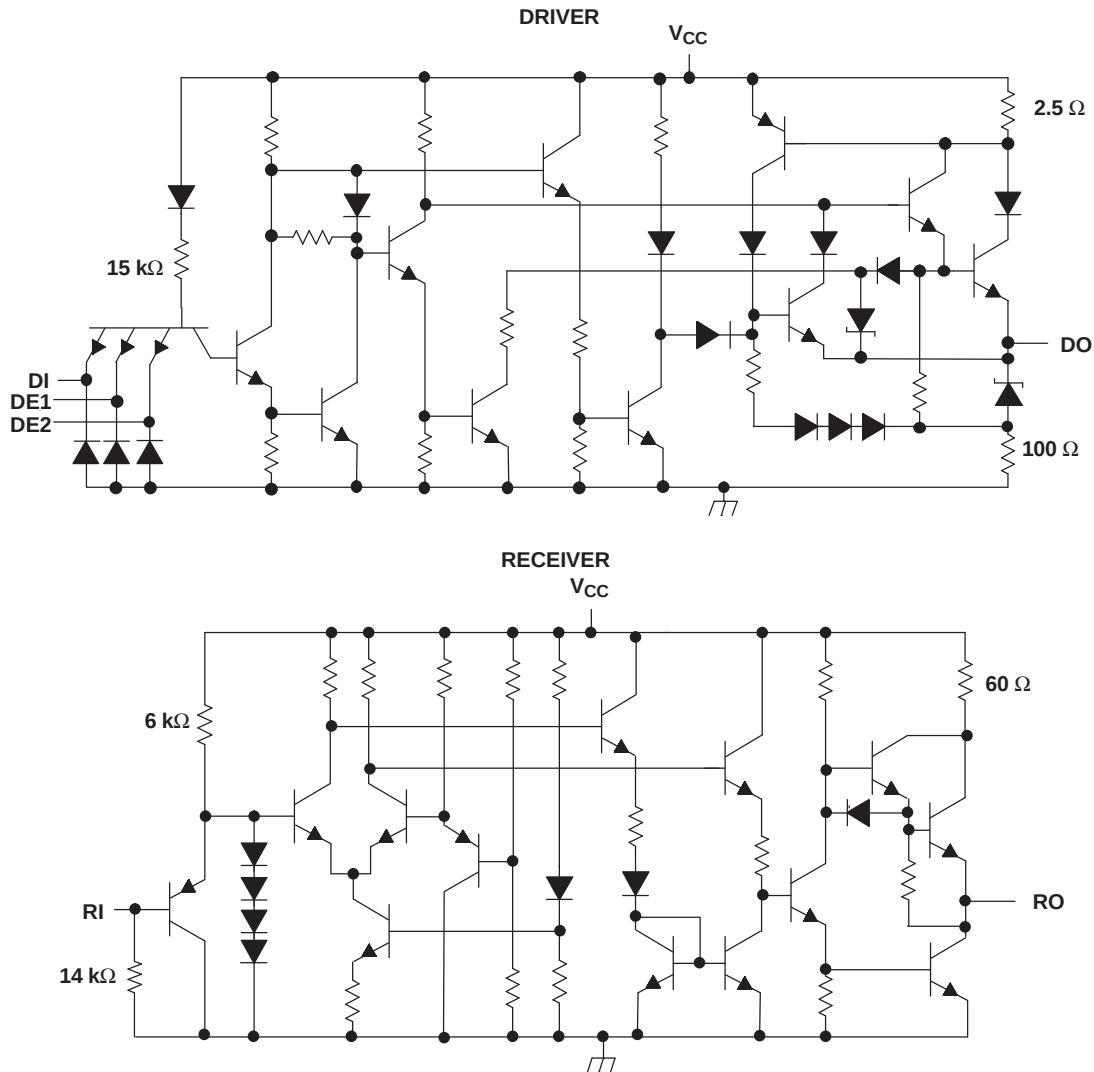
(1) H = high level, L = low level, X = irrelevant

LOGIC DIAGRAM (POSITIVE LOGIC)



Pin numbers shown are for the D and N package only.

EQUIVALENT SCHEMATICS OF DRIVER AND RECEIVER⁽¹⁾



(1) All resistor values are nominal.

SN751730

TRIPLE LINE DRIVER/RECEIVER

SLLS062E–MAY 1990–REVISED AUGUST 2007

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage ⁽²⁾			7	V
V _I	Input voltage range	Driver	–0.5	7	V
		Receiver	–0.5	7	V
V _O	Output voltage range	Driver	–0.5	7	V
	Enable input voltage range		–0.5	7	V
θ _{JA}	Package thermal impedance ⁽³⁾	D package		73	°C/W
		DW package		58	
		N package		67	
		NS package		60	
T _J	Operating virtual junction temperature			150	°C
	Lead temperature 1,6 mm (1/16 inch) from case for 10 s			260	°C
T _{stg}	Storage temperature range		–65	150	°C/W

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		4.75	5	5.25	V
V _{IH}	High-level input voltage	Driver, Enable	2			V
		Receiver	1.55			
V _{IL}	Low-level input voltage	Driver, Enable			0.8	V
		Receiver			1.15	
T _A	Operating free-air temperature		0		70	°C

DRIVER SECTION

Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
V_{IK}	Input clamp voltage	$V_{CC} = 4.75\text{ V}$,	$I_{IL} = -18\text{ mA}$		-1.5	V
V_{OH}	High-level output voltage	$V_{CC} = 4.75\text{ V}$, $I_{OH} = -59.3\text{ mA}$	$V_{IH} = 2\text{ V}$, $T_A = 25^\circ\text{C}$	3.11		V
		$V_{CC} = 5.25\text{ V}$, $I_{OH} = -78.1\text{ mA}$	$V_{IH} = 2\text{ V}$,		4.1	
		$V_{CC} = 4.75\text{ V}$, $R_L = 51.4\ \Omega$	$V_{IH} = 2\text{ V}$,	3.05		
		$V_{CC} = 5.25\text{ V}$, $R_L = 56.9\ \Omega$	$V_{IH} = 2\text{ V}$,		4.2	
V_{ODH}	Differential high-level output voltage	$R_L = 46.3\ \Omega$ or $56.9\ \Omega$			0.5	V
V_{OL}	Low-level output voltage	$V_{CC} = 5.25\text{ V}$, $V_{IL} = 0.8\text{ V}$, $V_{IH} = 4.5\text{ V}$	$I_{OL} = -0.24\text{ mA}$		0.15	V
			$R_L = 56.9\ \Omega$		0.15	
I_{IH}	High-level input current	$V_{CC} = 5.25\text{ V}$,	$V_{IH} = 2.7\text{ V}$		20	μA
					60	
I_{IL}	Low-level input current	$V_{CC} = 5.25\text{ V}$,	$V_{IH} = 0.4\text{ V}$		-400	μA
					-1200	
I_{OH}	High-level output current	$V_{CC} = 4.75\text{ V}$, $V_{OH} = 5\text{ V}$	$V_{IL} = 0$		100	μA
			$V_{IH} = 4.5\text{ V}$		100	
I_{OS}	Short-circuit output current ⁽¹⁾	$V_{CC} = 5.25\text{ V}$	$V_{IH} = 4.5\text{ V}$		-30	mA
I_{CCH}	Supply current (total package)	$V_{CC} = 5.25\text{ V}$, No load	$V_{I(D)} = 4.5\text{ V}$, $V_{I(R)} = 0$		47	mA
I_{CCL}			$V_{I(D)} = 0$, $V_{I(R)} = 4.5\text{ V}$		80	

(1) Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

Switching Characteristics

$V_{CC} = 5\text{ V} \pm 5\%$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	$R_L = 47.5\ \Omega$, See Figure 1		6.5	12	18.5	ns
t_{PHL}	Propagation delay time, high- to low-level output			6.5	12	18.5	ns
Δt_{pd}	Differential propagation delay time ⁽¹⁾					10	ns
t_r	Output rise time	$V_{CC} = 5\text{ V}$, $R_L = 47.5\ \Omega$, See Figure 1	$V_O = 0.15\text{ V}$ to 3.05 V , $C_L = 10.2\text{ pF}$,	5	10		ns
t_f	Output fall time			5	13		ns
SR	Slew rate	$V_O = 1\text{ V}$ to 3 V average, $R_L = 47.5\ \Omega$, See Figure 1	$C_L = 10.2\text{ pF}$,			0.65	V/ns

(1) $\Delta t_{pd} = |t_{PLH} - t_{PHL}|$

RECEIVER SECTION

Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
V_{OH}	High-level output voltage	$V_{CC} = 4.75\text{ V}$, $I_{OH} = -400\text{ }\mu\text{A}$	$V_I = 1.15\text{ V}$,	2.7		V
V_{OL}	Low-level output voltage	$V_{CC} = 4.75\text{ V}$, $V_{IH} = 1.55\text{ V}$	$I_{OL} = 8\text{ mA}$		0.5	V
			$I_{OL} = 4\text{ mA}$		0.4	
r_i	Input resistance	$V_{CC} = 0$,	$V_I = 0.15\text{ V to } 3.9\text{ V}$	7.4	20	k Ω
I_{IH}	High-level input current	$V_{CC} = 4.75\text{ V}$,	$V_{IH} = 3.11\text{ V}$		0.42	mA
I_{IL}	Low-level input current	$V_{CC} = 5.25\text{ V}$,	$V_{IL} = 0.15\text{ V}$	-0.24	0.04	mA
$I_{OS}^{(1)}$	Short-circuit output current	$V_{CC} = 5.25\text{ V}$,	$V_{IL} = 0$	-20	-100	mA
I_{CCH}	Supply current (total package)	$V_{CC} = 5.25\text{ V}$, No load	$V_{I(D)} = 4.5\text{ V}$, $V_{I(R)} = 0$		47	mA
I_{CCL}			$V_{I(D)} = 0$, $V_{I(R)} = 4.5\text{ V}$		80	

(1) Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

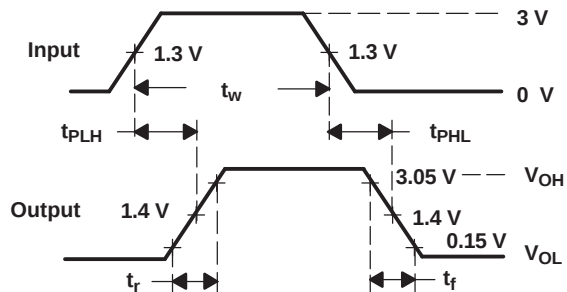
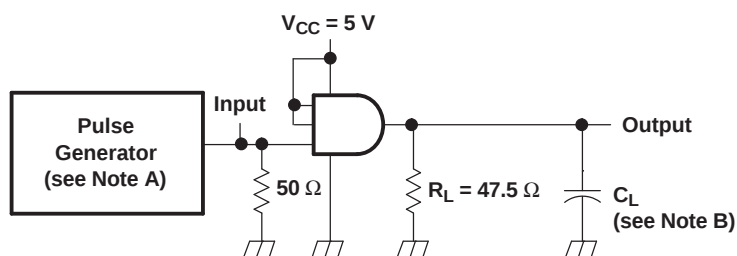
Switching Characteristics

$V_{CC} = 5\text{ V} + 5\%$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	$R_L = 2\text{ k}\Omega$, $C_L = 15\text{ pF}$, See Figure 2	7.5	12	19.5	ns
t_{PHL}	Propagation delay time, high- to low-level output		7.5	12	19.5	ns
$\Delta t_{pd}^{(1)}$	Differential propagation delay time				10	ns

(1) $\Delta t_{pd} = |t_{PLH} - t_{PHL}|$

PARAMETER MEASUREMENT INFORMATION

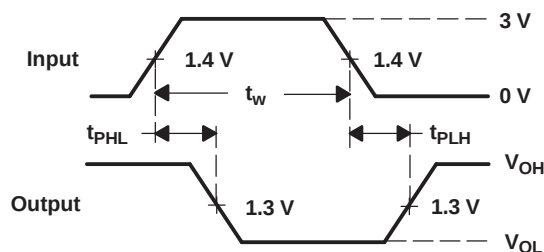
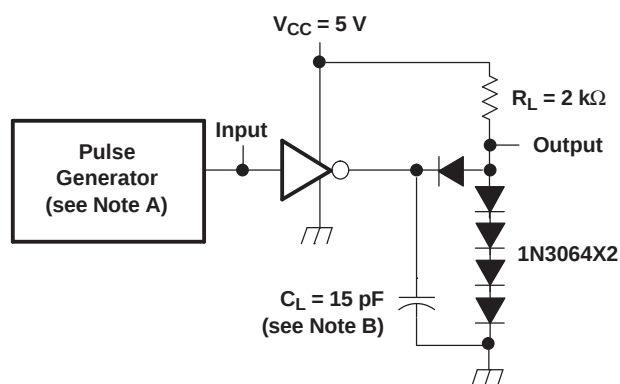


TEST CIRCUIT

VOLTAGE WAVEFORMS

NOTES: A. The pulse generator has the following characteristics: $Z_O \approx 50 \Omega$, $t_W \leq 500$ ns, $PRR \leq 1$ MHz, $t_f \leq 6$ ns, $t_r \leq 15$ ns.
B. C_L includes probe and jig capacitance.

Figure 1. Driver Test Circuit and Voltage Waveforms



TEST CIRCUIT

VOLTAGE WAVEFORMS

NOTES: A. The pulse generator has the following characteristics: $Z_O \approx 50 \Omega$, $t_W \leq 500$ ns, $PRR \leq 1$ MHz, $t_f \leq 10$ ns, $t_r \leq 10$ ns.
B. C_L includes probe and jig capacitance.

Figure 2. Receiver Test Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN751730D	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN751730
SN751730D.A	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN751730
SN751730DE4	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN751730
SN751730DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-	SN751730
SN751730DWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN751730
SN751730N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN751730N
SN751730N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN751730N

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN751730DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN751730DWR	SOIC	DW	20	2000	356.0	356.0	45.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN751730D	D	SOIC	16	40	507	8	3940	4.32
SN751730D.A	D	SOIC	16	40	507	8	3940	4.32
SN751730DE4	D	SOIC	16	40	507	8	3940	4.32
SN751730N	N	PDIP	16	25	506	13.97	11230	4.32
SN751730N.A	N	PDIP	16	25	506	13.97	11230	4.32

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



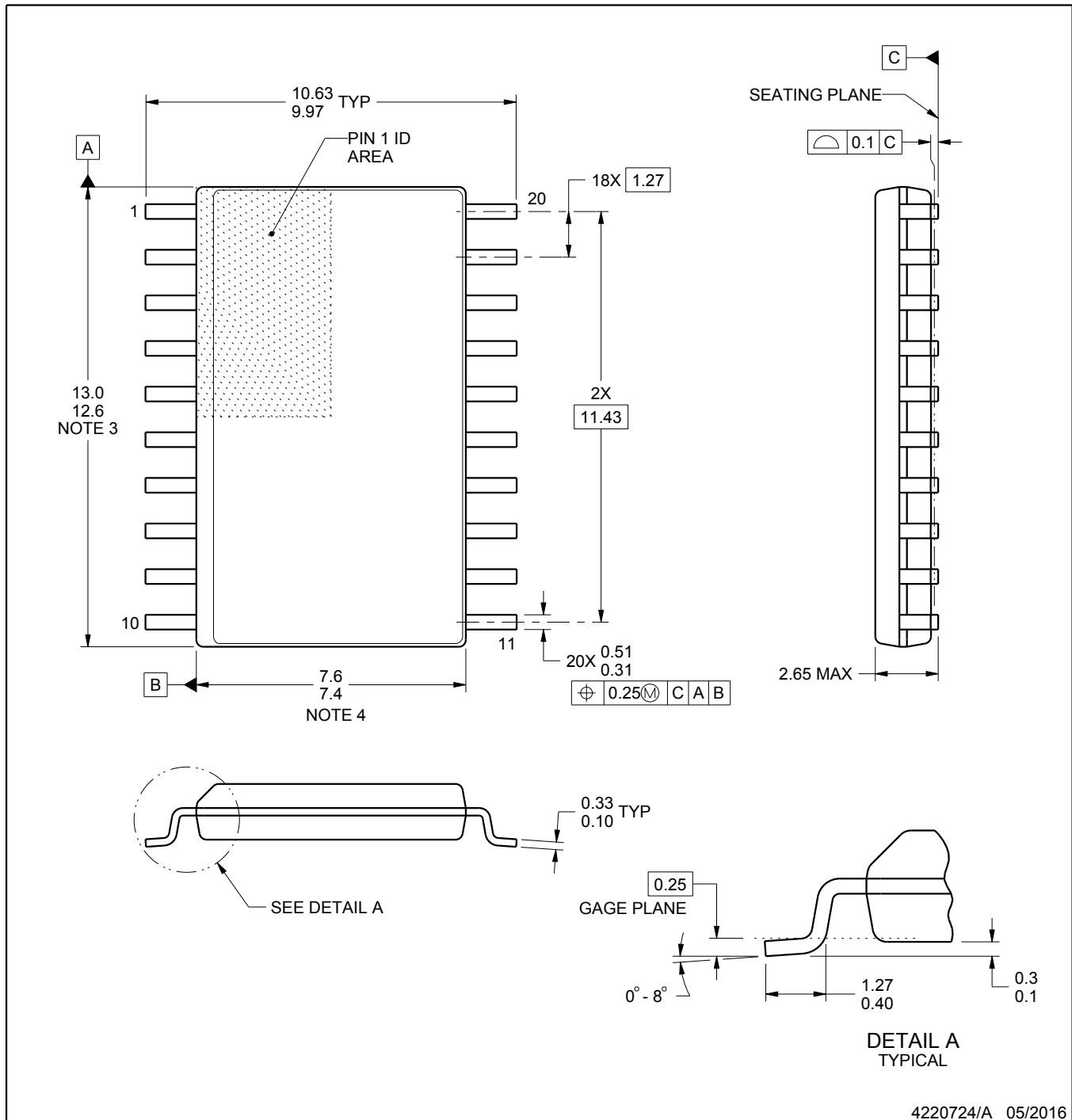
PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.



NOTES:

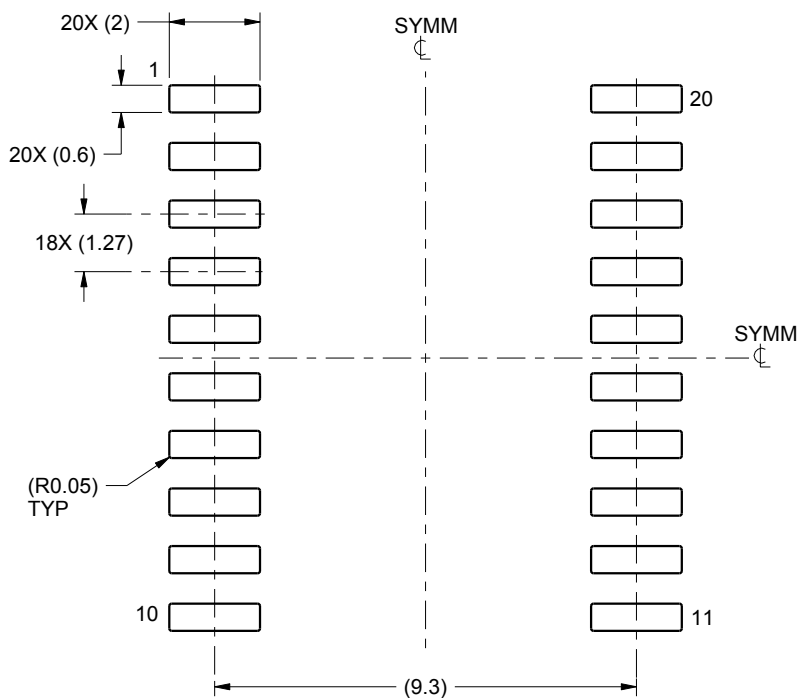
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

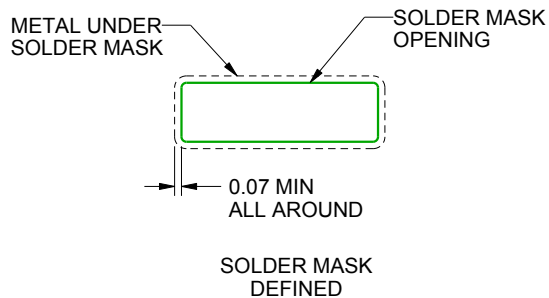
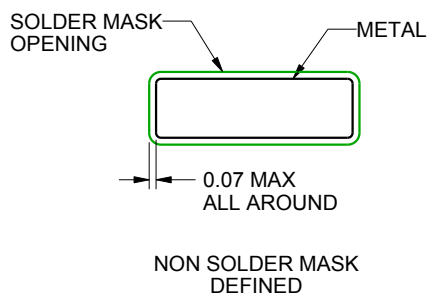
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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